

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0879660002](#)  
**Status:** **Active**  
**Description:** 1.00mm (.039") Pitch DDR2 DIMM Socket, SMT, 0.76µm (30µ") Gold (Au), 240 Circuit, Lead free

**Documents:**

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Drawing \(PDF\)](#)

**Agency Certification**

UL E29179

**General**

Product Family Memory Module Sockets  
 Series [87966](#)  
 Component Type Socket  
 JEDEC Outline MO-237  
 Product Name DDR2 DIMM

**Physical**

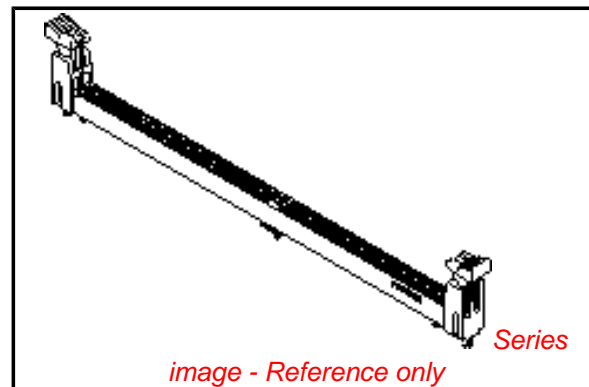
Circuits (Loaded) 240  
 Circuits (maximum) 240  
 Color - Resin Black  
 Durability (mating cycles max) 25  
 Entry Angle Vertical  
 Flammability 94V-0  
 Function Key None  
 Keying to Mating Part Yes  
 Material - Metal Brass, Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin  
 Material - Resin High Temperature Thermoplastic  
 PC Tail Length (in) 0.000 In  
 PC Tail Length (mm) 0.00 mm  
 PCB Locator Yes  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.000 In  
 PCB Thickness Recommended (mm) 0.00 mm  
 Packaging Type Tray  
 Pitch - Mating Interface (in) 0.039 In  
 Pitch - Mating Interface (mm) 1.00 mm  
 Pitch - Term. Interface (in) 0.039 In  
 Pitch - Term. Interface (mm) 1.00 mm  
 Plating min: Mating (µin) 30  
 Plating min: Mating (µm) 0.76  
 Plating min: Termination (µin) 100  
 Plating min: Termination (µm) 2.54  
 Temperature Range - Operating -10°C to +85°C  
 Termination Interface: Style Surface Mount

**Electrical**

Current - Maximum per Contact 1A  
 Voltage - Maximum 30V AC (RMS)/DC  
 Voltage Key Center

**Solder Process Data**

Duration at Max. Process Temperature (seconds) 3



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC**  
 Not Reviewed  
**Halogen-Free Status**  
**Not Reviewed**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**  
[87966Series](#)

Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	250

### **Material Info**

### **Reference - Drawing Numbers**

Product Specification	RPS-87966-001
Sales Drawing	SD-87966-002

This document was generated on 04/09/2010

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F F

E E

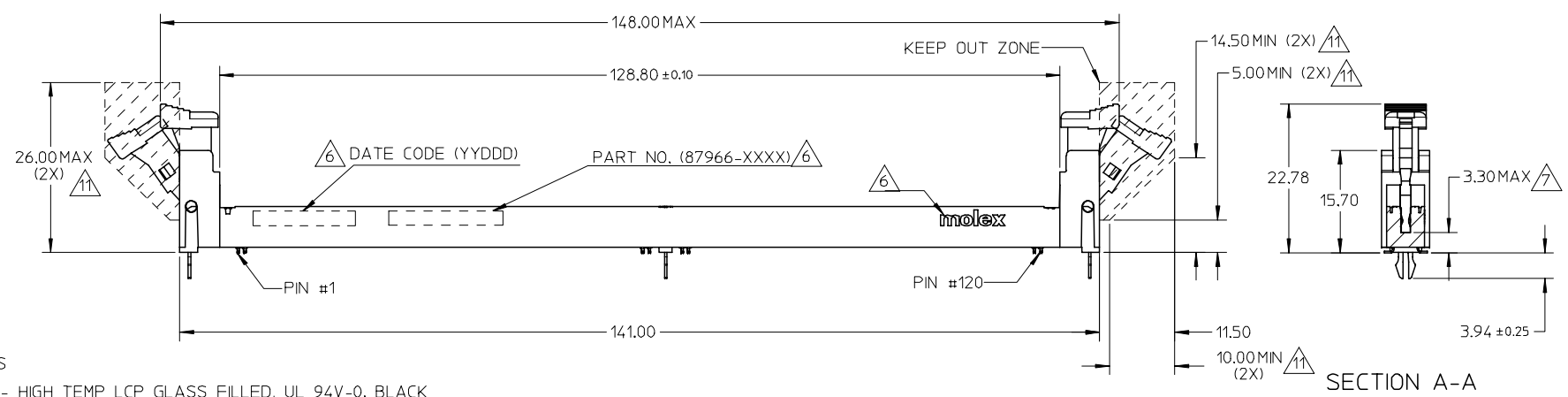
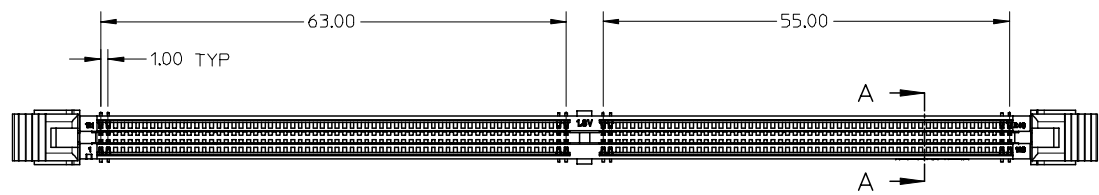
D D

C C

B B

A A

9 8 7 6 5 4 3 2 1

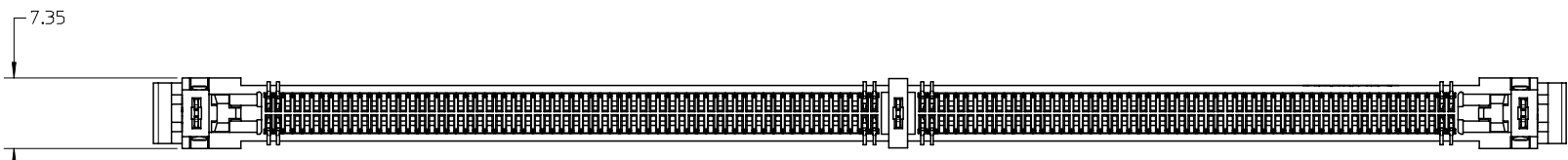


- NOTES:
- MATERIALS  
HOUSING - HIGH TEMP LCP GLASS FILLED, UL 94V-0, BLACK  
EJECTORS - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
  - PLATING OPTION - PLS REFER TO SHEET 5.
  - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED OVER PC PADS)
  - RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237. PLS REFER TO SHEET 3.
  - PRODUCT IS PACKED INTO TRAYS.
  - MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.
  - DIMM MODULE SEATING PLANE FROM TOP OF PCB.
  - COPLANARITY FOR SOLDER TAILS SHALL NOT EXCEED 0.20MM.
  - REFER TO PRODUCT SPEC. PS-87966-001 FOR PERFORMANCE SPECIFICATIONS.
  - THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.
  - KEEP OUT ZONE AS PER JEDEC SO-001.
  - CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

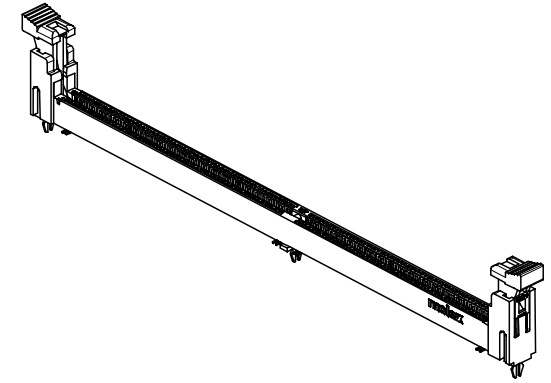
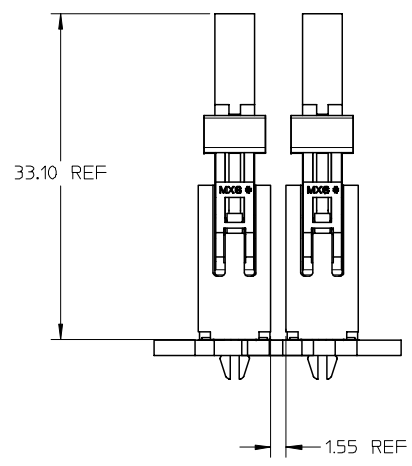
REVISED PAD SIZE EC NO: S2007-0667 DRWN: CCTEH CHKD: SRAMESH APPR: SHLENI	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CCTEH	DATE 2005/10/19	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT			
		4 PLACES	± ---	± ---	CHECKED BY SRAMESH	DATE 2005/11/21	MATERIAL NO.			
		3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2005/11/21	DOCUMENT NO. SD-87966-002			
			2 PLACES	± 0.10	± ---	MOLEX INCORPORATED				
			1 PLACE	± ---	± ---	SHEET NO. 1 OF 5				
			ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			
B1	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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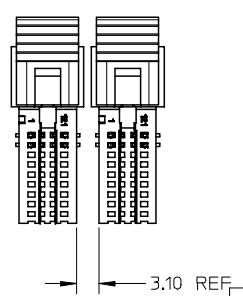
E



D

C

B



A

REVISED PAD SIZE  
 EC NO: S2007-0667  
 DRWN: CCTEH  
 CHKD: SRRAMESH  
 APPR: SHLENI

DESCRIPTION  
 2007/02/08  
 2007/02/08  
 2007/02/09

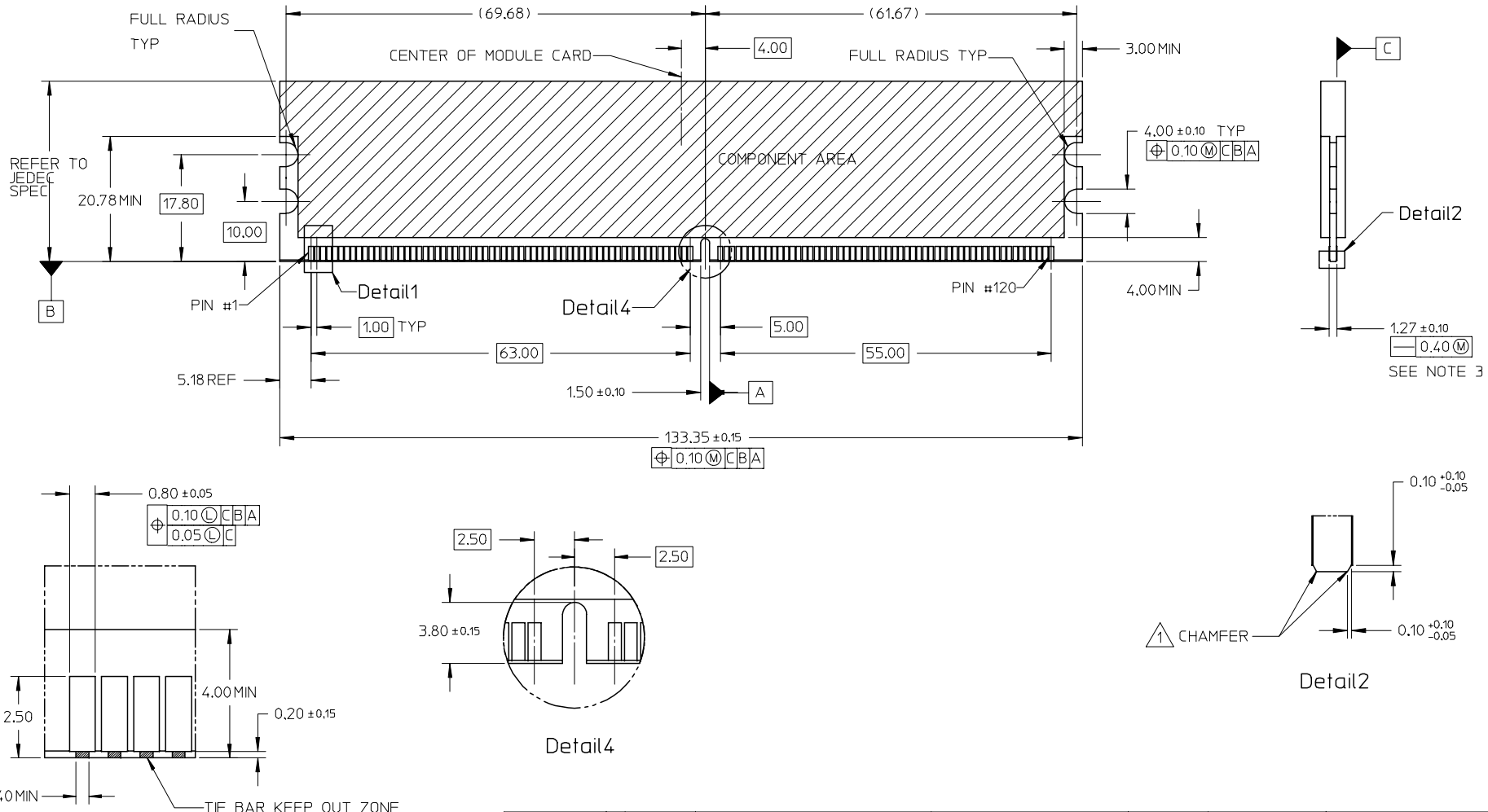
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
▽=0	mm INCH
∇=0	4 PLACES ± --- ± ---
	3 PLACES ± --- ± ---
	2 PLACES ± 0.10 ± ---
	1 PLACE ± --- ± ---
	ANGULAR ± 1 °
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT	
CCTEH	2005/10/19			
CHECKED BY	DATE	MOLEX INCORPORATED		
SRRAMESH	2005/11/21			
APPROVED BY	DATE	SD-87966-002		
GGLEE	2005/11/21			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
	SEE TABLE	2 OF 5		

SIZE  
 A3  
 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

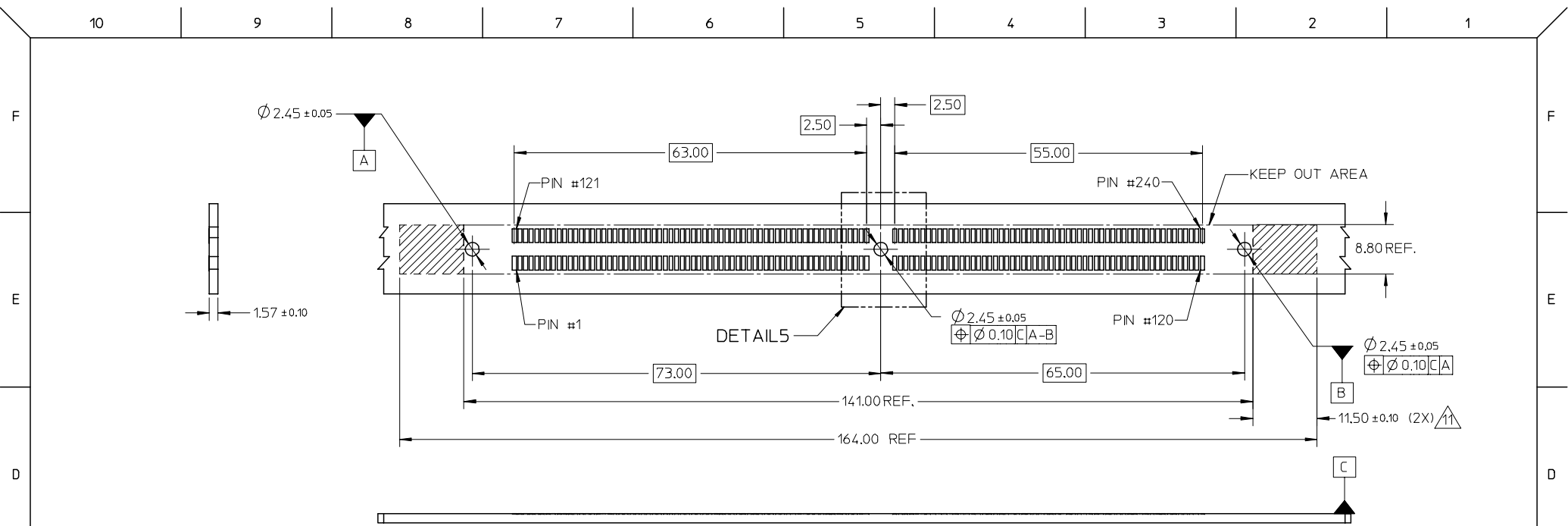
9 8 7 6 5 4 3 2 1

# RECOMMENDED MODULE LAYOUT

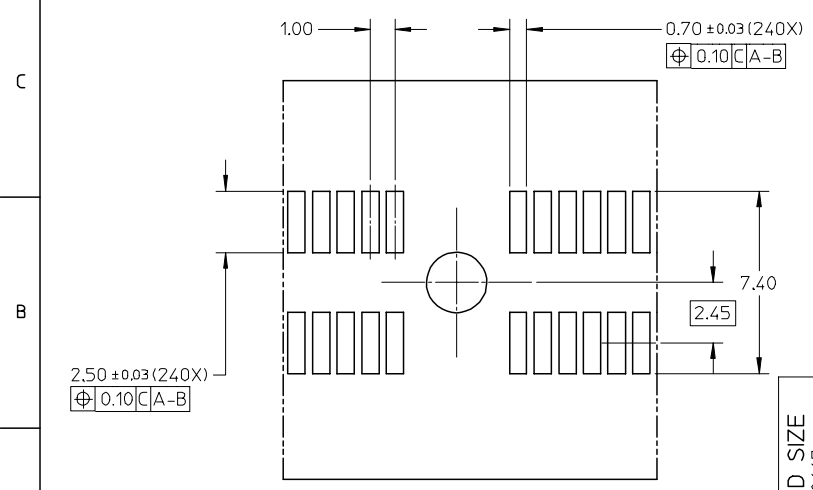


NOTES:  
 1. MODULE CARD USED IN PRODUCT TESTING ARE CHAMFER.

REVISED PAD SIZE EC NO: S2007-0667 DRWN: CTEH CHKD: SRAMESH APPR: SHLENI	2007/02/08	2007/02/08	2007/02/08	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DESCRIPTION	DATE	DATE		DATE	DATE	DATE	DATE	DATE	TITLE	MOLEX INCORPORATED
	REV	DATE	DATE		DATE	DATE	DATE	DATE	DATE	DATE	
B1	2007/02/09	2007/02/08	2007/02/08	2007/02/08	2007/02/08	2007/02/08	2007/02/08	2007/02/08	2007/10/19	2005/11/21	2005/11/21
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					ANGULAR ± 1 °		SEE TABLE		SD-87966-002		SHEET NO. 3 OF 5



RECOMMENDED STENCIL THICKNESS = 150µM.



DETAILS 5

<b>REVISED PAD SIZE</b> EC NO: S2007-0667 DRWN: CCTEH CHKD: SRRAMESH APPR: SILENI	2007/02/08 2007/02/08 2007/02/09	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY CCTEH	DATE 2005/10/19	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, SMT				
			4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2005/11/21					
			3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2005/11/21					
		ANGULAR ± 1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87966-002		4 OF 5						

10 9 8 7 6 5 4 3 2 1

ASSEMBLY PART NO.	VOLTAGE KEY POS.	PLATING	LATCH COLOR	LUBRICATION
87966-0001	CENTRE 1.8V	0.76µM (30µ IN) MIN. GOLD ON CONTACT	BLACK	NO
87966-0002		2.54µM (100µ IN) MIN. TIN ON SOLDER TAILS		YES
		1.27µM (50µ IN) MIN. NICKEL UNDERPLATE		

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		4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2005/11/21	MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2005/11/21	DOCUMENT NO. SD-87966-002	SHEET NO. 5 OF 5		
B1	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1